

Title (en)

Method for sealing a device such as an induction coil

Title (de)

Verfahren zum Abdichten einer Vorrichtung wie einer Induktionspule

Title (fr)

Procédé d'étanchéification d'une pièce telle qu'une bobine d'induction

Publication

**EP 0511062 B1 19960717 (FR)**

Application

**EP 92401090 A 19920417**

Priority

FR 9105120 A 19910425

Abstract (en)

[origin: EP0511062A1] Method for sealing a device such as an induction coil and mould for carrying out the method. The subject of the invention is a method for sealing a device such as an induction coil. For this purpose, the device is shrouded in a heat-settable vinyl resin (3). <IMAGE>

IPC 1-7

**H01F 41/12**; B05D 1/00

IPC 8 full level

**B29C 67/00** (2006.01); **H01F 41/12** (2006.01); **B29K 27/06** (2006.01); **B29L 31/34** (2006.01)

CPC (source: EP)

**H01F 41/127** (2013.01)

Citation (examination)

- DERW/WPI,Jap.Abs.80-24601C,8014
- DERW/WPI,Jap.Abs.78-59808A,7833
- DERW/WPI,Jap.Abs.90-182614,9024
- DERW/WPI,Jap.Abs.82-04654E,8203
- Pat.Abs.Jap.13,no.42.,30/01/89

Designated contracting state (EPC)

AT BE CH DE DK ES FR GB GR IT LI LU MC NL PT SE

DOCDB simple family (publication)

**EP 0511062 A1 19921028**; **EP 0511062 B1 19960717**; AT E140558 T1 19960815; DE 69212208 D1 19960822; DE 69212208 T2 19970220; FR 2675943 A1 19921030; FR 2675943 B1 19941021; JP H05124114 A 19930521

DOCDB simple family (application)

**EP 92401090 A 19920417**; AT 92401090 T 19920417; DE 69212208 T 19920417; FR 9105120 A 19910425; JP 10699792 A 19920424